PNP -100mA -50V Digital Transistors (Bias Resistor Built-in Transistors)

**Datasheet** 

#### **AEC-Q101 Qualified**

DTA144TKAFRA

SOT-346(SC-59)

Parameter	Value
$V_{\sf CEO}$	-50V
I <sub>C</sub>	-100mA
R <sub>1</sub>	47kΩ

## Features

- 1) Built-In Biasing Resistor
- 2) Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) The bias resistors consist of thin-film resistors with complete isolation to allow negative biasing of the input. They also have the advantage of completely eliminating parasitic effects.
- 4) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 5) Complementary NPN Types: DTC144T series
- 6) Lead Free/RoHS Compliant.

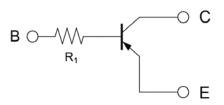
# VMT3 COLLECTOR BASE EMITTER DTA144TMFHA (SC-105AA) UMT3 COLLECTOR COLLECTOR DTA144TEFRA SOT-416(SC-75A) UMT3 COLLECTOR SMT3 COLLECTOR

#### •Inner circuit

DTA144TUAFRA

SOT-323(SC-70)

Outline



## Application

Switching circuit, Inverter circuit, Interface circuit,

Driver circuit

B: BASE

C: COLLECTOR

E: EMITTER

#### Packaging specifications

or ackaging specifications							
Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
DTA144TMFHA	VMT3	1212	T2L	180	8	8000	96
DTA144TEFRA	EMT3	1616	TL	180	8	3000	96
DTA144TUAFRA	UMT3	2021	T106	180	8	3000	96
DTA144TKAFRA	SMT3	2928	T146	180	8	3000	96

# ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Pa	Parameter			Unit
Collector-base voltage			-50	V
Collector-emitter voltage		V <sub>CEO</sub>	-50	V
Emitter-base voltage			-5	V
Collector current			-100	mA
	DTA144TMFHA		150	mW
Davis a dia sin ation	DTA144TEFRA	D *1	150	
Power dissipation	DTA144TUAFRA	P <sub>D</sub> *1	200	
		200		
Junction temperature			150	°C
Range of storage temperature			-55 to +150	°C

# • Electrical characteristics $(T_a = 25^{\circ}C)$

Darameter	Cumbal	Conditions		Values		
Parameter	Symbol	Symbol Conditions -		Min. Typ. Max.		Unit
Collector-base breakdown voltage	BV <sub>CBO</sub>	BV <sub>CBO</sub> I <sub>C</sub> = -50μA		-	-	V
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = -1mA	-50	-	-	V
Emitter-base breakdown voltage	BV <sub>EBO</sub>	I <sub>E</sub> = -50μA	-5	-	-	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = -50V	-	-	-0.5	μA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = -4V	-	1	-0.5	μA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{C} / I_{B} = -5 \text{mA} / -0.5 \text{mA}$	-	-	-0.3	V
DC current gain	h <sub>FE</sub>	$V_{CE} = -5V, I_{C} = -1mA$	100	250	600	-
Input resistance	R <sub>1</sub>	-	32.9	47	61.1	kΩ
Transition frequency	f <sub>T</sub> *2	V <sub>CE</sub> = -10V, I <sub>E</sub> = 5mA, f = 100MHz	-	250	-	MHz

<sup>\*1</sup> Each terminal mounted on a reference footprint

<sup>\*2</sup> Characteristics of built-in transistor

# ● Electrical characteristic curves(Ta=25°C)

Fig.1 Grounded emitter propagation characteristics

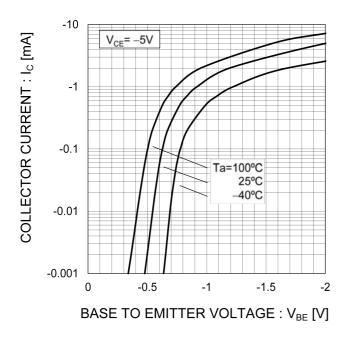


Fig.2 Grounded emitter output characteristics

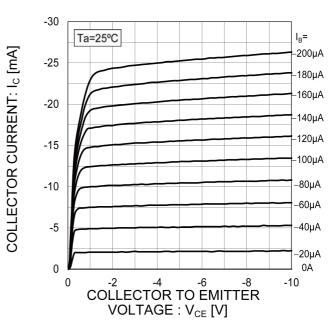


Fig.3 DC Current gain vs. Collector Current

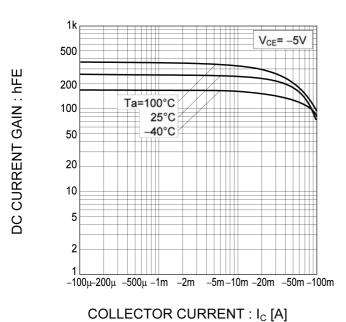
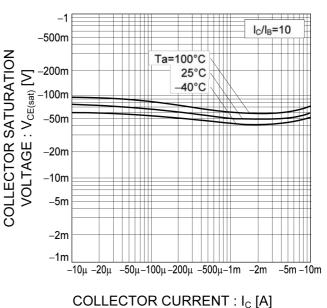
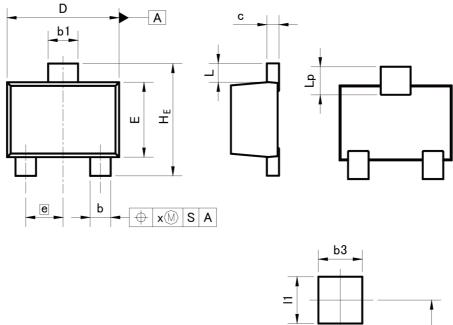


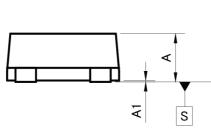
Fig.4 Collector-emitter saturation voltage vs.

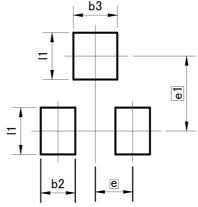
Collector Current



VMT3







Pattern of terminal position areas [Not a recommended pattern of soldering pads]

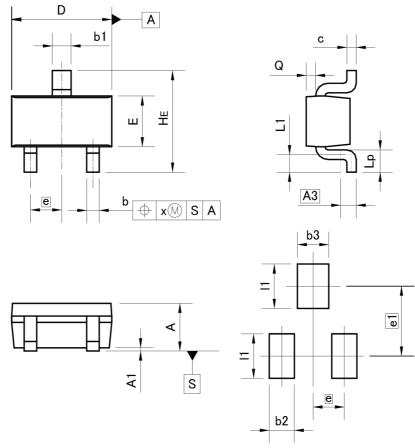
DIM -	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
С	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
е	0.4	0.40 0.0		02
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
х	=	0.10	=	0.004

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	(2)	0.37		0.015
b3	=	0.47	100	0.019
e1	0.80		0.0	031
11	-	0.50	-	0.020

Dimension in mm/inches



EMT3



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

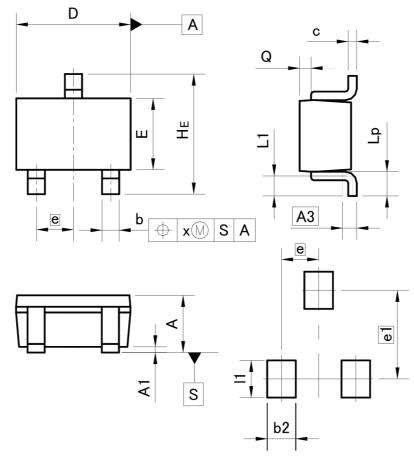
DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.50		0.0	20
HE	1.40	1.80	0.055	0.071
L1	0.10	<del></del> :	0.004	
Lp	0.15	<del>55</del> 3:	0.006	TT.
Q	0.05	0.25	0.002	0.010
x	<b>—</b> 1	0.10	_	0.004

DIM	MILIME	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	77.L	0.40	-32	0.016
b3	<del></del>	0.50	÷.	0.020
e1	1.10		0.0	043
11	49	0.70	-	0.028

Dimension in mm/inches



UMT3



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

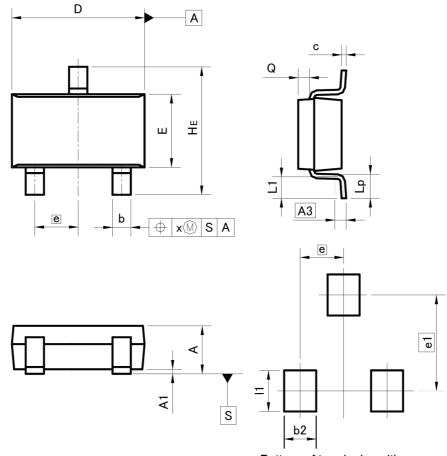
DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.2	25	0.0	10
b	0.15	0.30	0.006	0.012
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.0	35	0.0	26
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
x	=	0.10	=	0.004

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2		0.50		0.020
e1	1.55		0.0	061
11	_	0.65	_	0.026

Dimension in mm/inches



SMT3



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.	0.95		37
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x	2	0.10		0.004
у	927)	0.10		0.004
	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	=	0.60	_	0.024
e1	2.	10	0.0	10000
	2.10		0.000	

Dimension in mm/inches

e1



0.035

0.90

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  - [c] the Products are exposed to direct sunshine or condensation
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